

CLAIMS

What is claimed is:

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1. A microelectronic device package comprising:
a substantially flat electrical connector formed from a metal frame;
a die attach pad electrically isolated from said connector, said pad having a
bottom surface; and
an encapsulant surrounding a portion of said electrical connector and a portion of
said die attach pad,
wherein said bottom surface of said die attach pad is substantially free of
encapsulant.
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2. The microelectronic device package according to claim 1, wherein said connector
and said pad are formed from a leadframe.
3. The microelectronic device package according to claim 1, wherein said connector
and said pad are formed by etching a sheet of conductive material having removable material
attached thereto.
4. The microelectronic device package according to claim 1, wherein said
encapsulant is molded onto a portion of said conductor and a portion of said pad, wherein said
connector and said pad are attached to removable tape, and wherein said tape inhibits attachment
of said encapsulant to said bottom surface of said pad.
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5. The microelectronic device package according to claim 1, further comprising a
plurality of rows of connectors located about a perimeter of said pad.

6. An electronic device package configured to facilitate electrical connection between a device and a substrate, said package comprising:

- a plurality of electrical connectors formed by etching a sheet of conductive material; and
- an encapsulant attached to a portion of each of said plurality of electrical connectors,

wherein said encapsulant is molded to each said portion by exposing said electrical connectors and a removable material attached to said connectors to a mold process.

7. The electronic device package of claim 6, further comprising a die attach pad proximate said connectors and electrically isolated from said connectors.

8. The electronic device package of claim 6, wherein said plurality of electrical connectors form a plurality of rows about a perimeter of the device.

9. The electronic device package of claim 6, wherein said connectors are formed from a leadframe.

10. A method for forming a package for an electrical device, said method comprising the steps of:

attaching a removable material to a surface of a conductive material;
forming isolated conductive features within said conductive material;
attaching encapsulant to said isolated conductive features and said removable
material; and
removing said removable from said conductive features and said encapsulant.

11. The method for forming a package for the electronic device of claim 10, wherein said forming step includes patterning a surface of said conductive material with a material resistant to an etchant and etching said conductive material with said etchant.

12. The method for forming a package for the electronic device of claim 10, further comprising the step of forming a die attach pad within said conductive material.

13. The method for forming a package for the electronic device of claim 10, further comprising the step of coupling the device to said die attach pad.

14. The method for forming a package for an electronic device of claim 10, further comprising the step of electrically coupling an input/output portion of the device to said isolated conductive feature.

15. The method for forming a package for the electronic device of claim 10, further comprising the step of singulating individual packaged devices.

16. A method of forming a device package, said method comprising the steps of:
applying removable material to a leadframe;
attaching a device to said leadframe; and
attaching encapsulant to a portion of said device and a portion of said leadframe.

17. The method of forming a device package according to claim 16, further comprising the step of exposing said leadframe to an etchant to form undercut regions configured to assist attachment of said encapsulant to said leadframe.

18. The method of forming a device package according to claim 16, further comprising the step of electrically coupling a portion of said device to said leadframe.

19. The method of forming a device package according to claim 16, further comprising the step of forming isolated conductive features by sawing through a portion of said leadframe.

20. The method of forming a device package according to claim 16, further comprising the step of removing said removable material from said leadframe and said encapsulant.

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